LNJ03004BND3

Surface Mounting Chip LED

3230 Type

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	430	mW	
Forward current *1	I_F	120	mA	
Pulse forward current *2	I_{FP}	200	mA	
Junction temperature	Tj	110	°C	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

■ Lighting Color

• White (5000 [Kelvin])

Note) *1: I_F is different by radiated factor of evaluation board.

This value is mounted on evaluation board at Rthj-a = 35.0 °C/W.

*2: The condition of pulse current I_{FP} is 55 ms pulse width, 10 % duty.

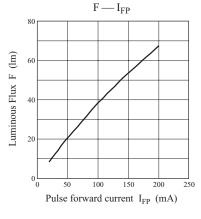
■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

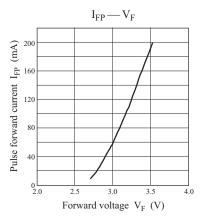
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage *1	V _F	$I_{FP} = 60 \text{ mA}$	2.6	3.0	3.4	V
Luminous flux *2	F	$I_{FP} = 60 \text{ mA}$	18.0	24.3	36.0	lm
Chromaticity coordinates *3	X	$I_{FP} = 60 \text{ mA}$		0.345		_
	у	$I_{FP} = 60 \text{ mA}$		0.355		_
Color Rendering Index	Ra	$I_{FP} = 60 \text{ mA}$		82		_

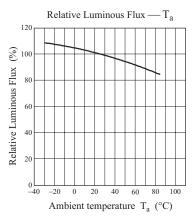
Note) *1: Complete Forward Voltage measurement within 0.1 seconds. Tolerance $\pm 3\%$

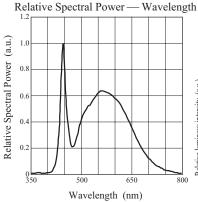
*2: Complete Luminous flux measurement within 0.1 seconds. Tolerance ±10%

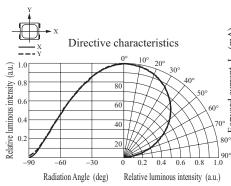
 $*3: \ Complete \ Chromaticity \ coordinates \ measurement \ within \ 0.1 \ seconds. \ Tolerance \ of \ chromaticity \ is \ \pm 0.01$

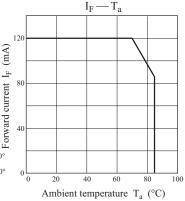




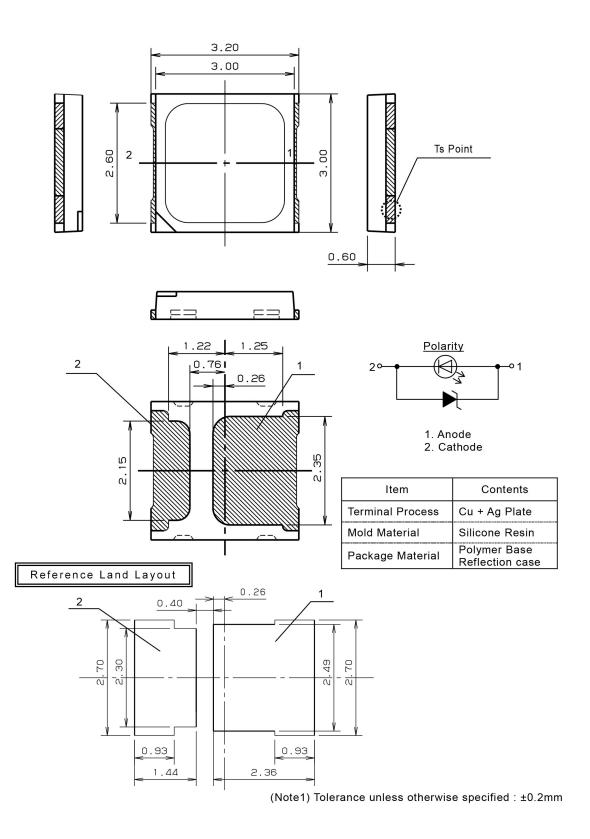








■ Package (Unit: mm)



Ver. DEK 2

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